

Material Designation	Chemical Composition (%)	Applications
ASTM C10300 JIS C1030 INDIAN Cu-HCP EN CW021A BS -	Cu ≥ 99.95 P 0.002 - 0.007	Telecommunication Cables Power Distribution Systems Cooling Elements Electrical & Electronic Applications

Specification	Properties
Thickness 0.025 - 5 mm ID 80 - 500 mm	Formability Excellent
Width 4 - 1220 mm OD -	Welding Ability Good
Length - Coil Wt 10 - 2000 Kg	Electrical Conductivity Good
Temper O , 1/4H , 1/2H , 3/4H , H , EH , SH	Thermal Conductivity Good

## Description

Cu-HCP is a high purity, high conductivity, low phosphorus Copper. This copper may be heat treated, welded and brazed without need for special precautions to avoid hydrogen embrittlement.HCP copper is alloyed with small amount 20 - 70 ppm of phosphorous. This small quantity of phosphorous will not reduce significantly the electrical and thermal conductivity of the alloy but help to obtain homogenous grain size in the product.

## Value Proposition

- Competitive Pricing
- Flexible LME price fixation
- Product Customization

- Quality Assurance
- Committed to deliveries
- Standard export pallet packing

This data is general technical specification; Binding technical specifications will be as per agreement.

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